

# CuSn0.15

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Comparable standards: UNS C14415 • EN CW117C  
 Aurubis designations: PNA 216 • CuSn0.15

**Description** CuSn0.15 is solid solution strengthened by a small tin addition. It has increased strength as well as good electrical and thermal conductivity. Moreover the alloy exhibits an increased temperature stability compared to highest conductive copper alloys. The alloy can be well formed, exhibits a good corrosion resistance and is suited for soldering, brazing and welding.

**Composition**

Cu	Sn
[%]	[%]
rem	0.10-0.15

Composition of this alloy is in accordance with RoHS for electric & electronic components and ELV for the automotive industry.

**Physical properties**

Melting point	Density	c <sub>p</sub> @ 20°C	Young's modulus	Thermal cond.	Electrical cond.		α @20-300°C
[°C]	[g/cm³]	[kJ/kgK]	[GPa]	[W/mK]	[MS/m]	[%IACS]	[10 <sup>-6</sup> /K]
1081	8.93	0.385	130	340	≥ 47	≥81	17.3

Note: The specified conductivity applies to the soft condition only.

c<sub>p</sub> specific heat capacity  
 α coefficient of thermal expansion

**Mechanical properties**

	Tensile Strength	Yield Strength	Elongation A <sub>50</sub>	Hardness HV	Bend ratio 90° [r]		Bend ratio 180° [r]	
	[MPa]	[MPa]	[%]	[-]	GW	BW	GW	BW
R250	250-320	≥ 200	≥ 9	60-90	0	0	0	0
R300	300-370	≥ 250	≥ 4	85-110	0	0		
R360	360-430	≥ 300	≥ 3	105-130	0	0		
R420	420-490	≥ 350	≥ 2	120-140	1	1		

r = x \* t (thickness t ≤ 0.5mm)  
 GW bend axis transverse to rolling direction. BW bend axis parallel to rolling direction.

**Fabrication properties**

Cold formability	excellent
Hot formability	excellent
Soldering	excellent
Brazing	excellent
Oxyacetylene welding	fair
Gas shielded arc welding	good
Resistance welding	not recommended
Machinability	not recommended

**Electrical conductivity**

The electrical conductivity depends on chemical composition, the level of cold deformation and the grain size. A high level of deformation as well as a small grain size decrease the conductivity.

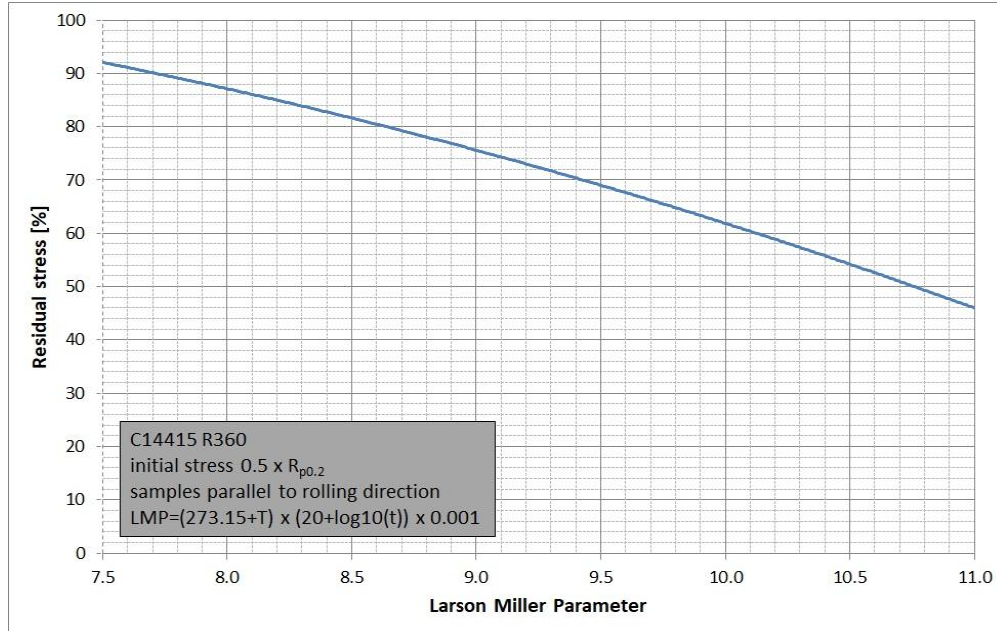
**Corrosion Resistance**

Copper is resistant to: Natural and industrial atmospheres as well as maritime air, drinking and service water, non oxidizing acids, alkaline solutions and neutral saline solutions.  
 Copper is not resistant to: Ammonia, halogenide, cyanide and hydrogen sulfide solutions and atmospheres, oxidizing acids and sea water (especially at high flow rates).  
 CuSn0.15 has an improved resistance to pitting- and erosion corrosion compared to Cu-DHP.

**Typical uses**

Automotive, components of electrical engineering, connectors, leadframes

**Relaxation Behaviour**



Stress relaxation data shown as residual stress against Larson Miller Parameter. The Larson Miller Parameter represents temperature and time.  
 Test method: Mandrel test according to ASTM E328.

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